

FIG. 3

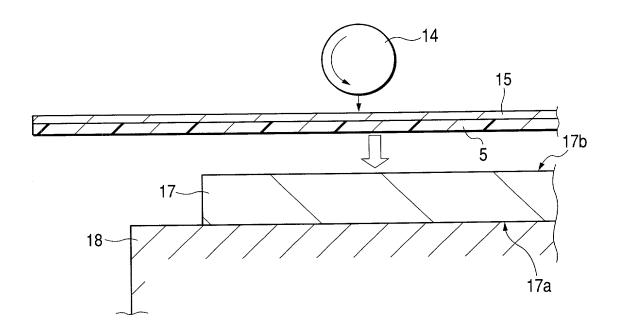
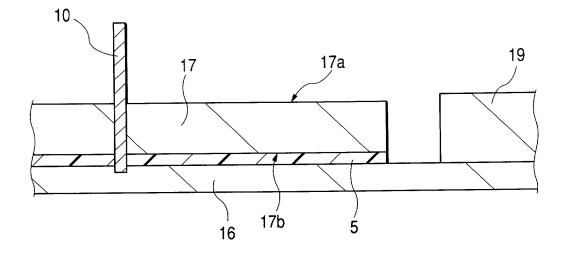


FIG. 4



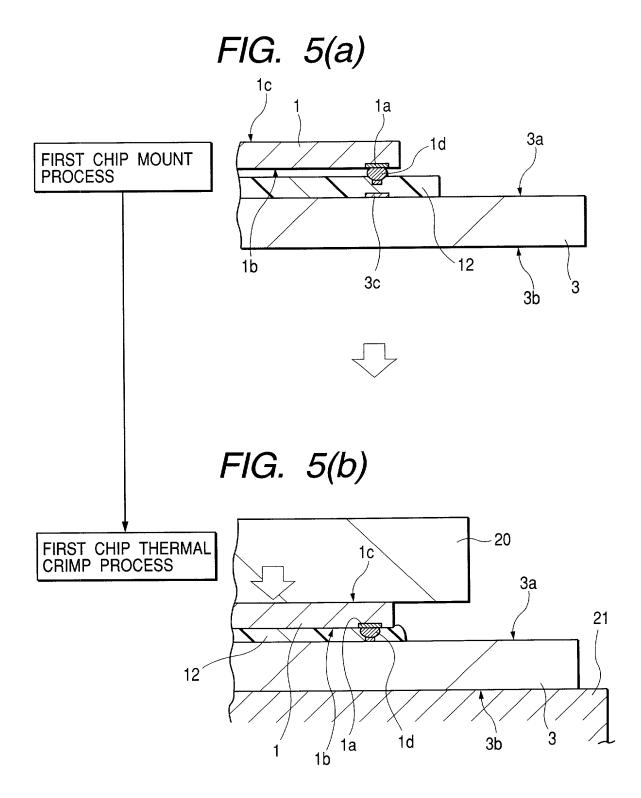


FIG. 6(a)

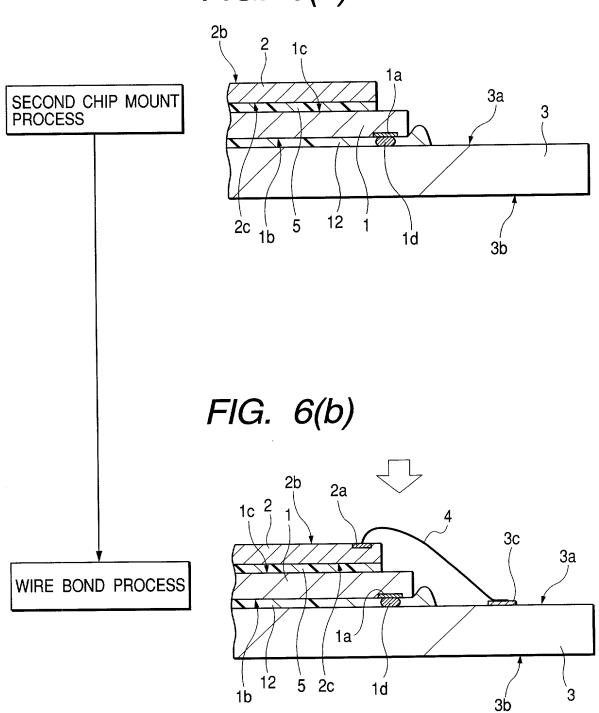


FIG. 7

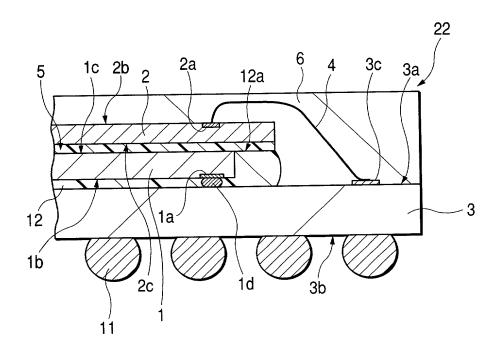


FIG. 8

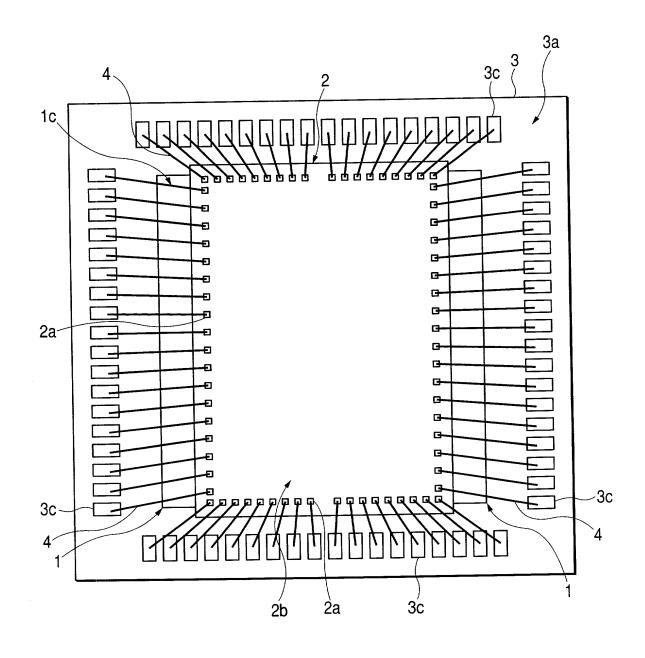


FIG. 9(a)

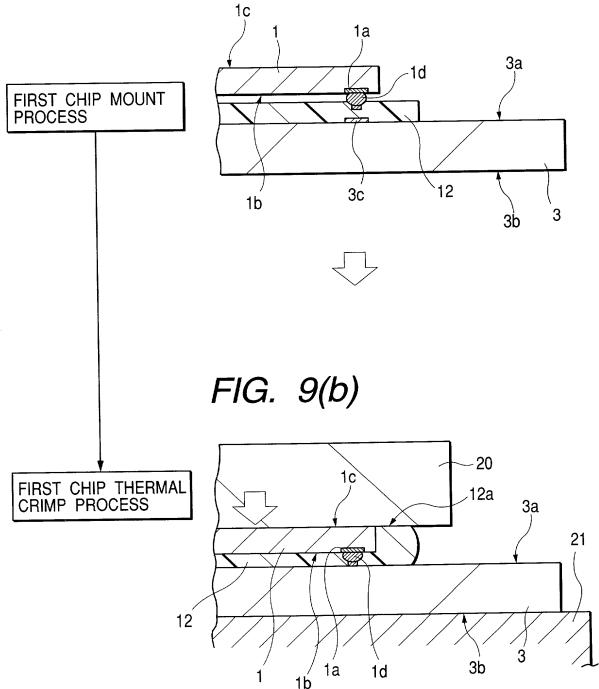
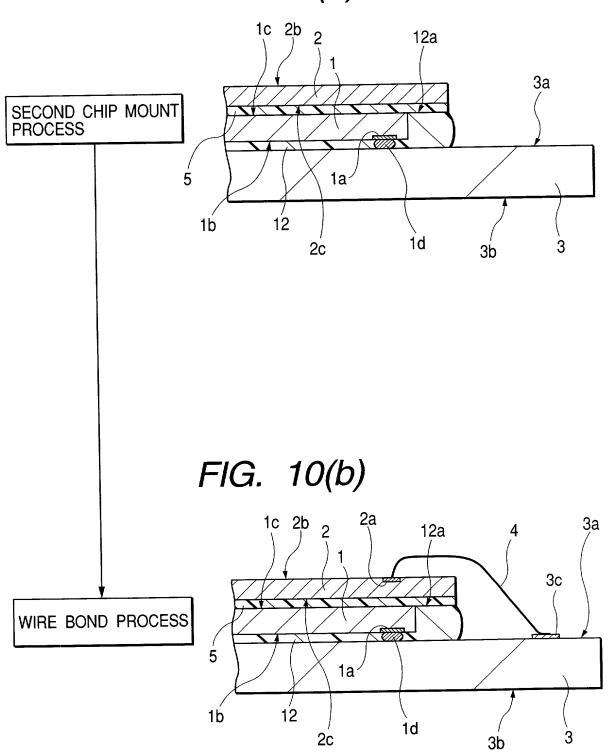


FIG. 10(a)



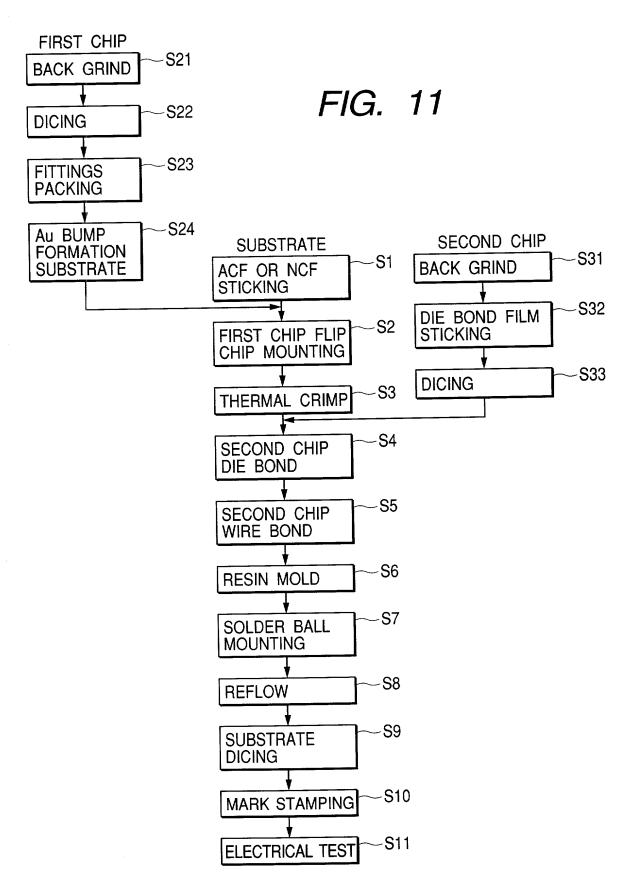


FIG. 12

	PRO	OCESS
PROCESS FLOW	NO.	PROCESS NAME
1	1	FIRST CHIP
∇	2	BACK GRIND
$\frac{7}{2}$ 0 03 $\frac{4}{2}$	3	DICING, FITTINGS PACKING
1 V 9 Q3 Y	4	BUMP Au WIRE
b8	5	BUMP BONDING
♦10 ♦6	6	EXTERNAL INSPECTION
Q11 12	7	BUMP BONDING
14	8	SUBSTRATE BAKE
∫	9	CHIP MOUNT RESIN FILM
015	10	CHIP MOUNT RESIN FILM STICKING
016	11	CHIP MOUNT, CRIMP
Q 17 18	12	SECOND CHIP
I \[\rangle	13	BACK GRIND
019 21	14	CHIP MOUNT RESIN FILM
	15	CHIP MOUNT RESIN FILM STICKING
22 23	16	DICING
\(\nabla \)	17	DIE BOND
Q 24	18	Au WIRE
\ \ \QDD 25	19	WIRE BOND
♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦ ♦	20	EXTERNAL INSPECTION
\ \ \ \ \ \ 27	21	SEAL RESIN
♦ 28	22	MOLD
♦ 29	23	SOLDER BALL
♦30	24	BALL MOUNTING
∫ 3 1	25	CLEANING
	26	EXTERNAL INSPECTION
1	27	SUBSTRATE DICING
	28	MARK
	29	ELECTRICAL TEST
	30	EXTERNAL INSPECTION
	31	PACKING

FIG. 13

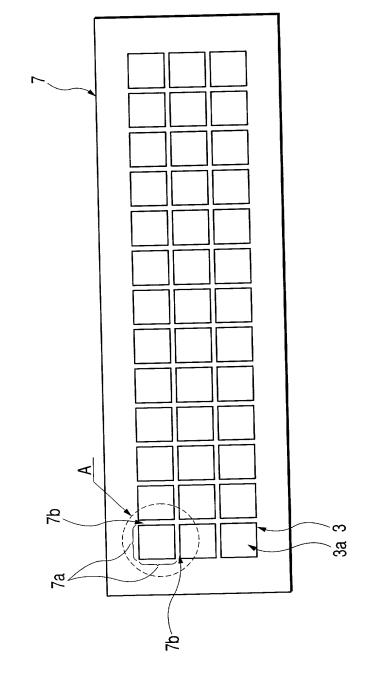
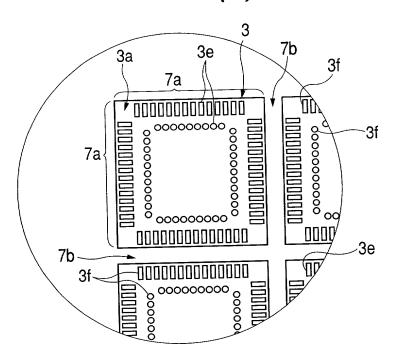


FIG. 14(a)



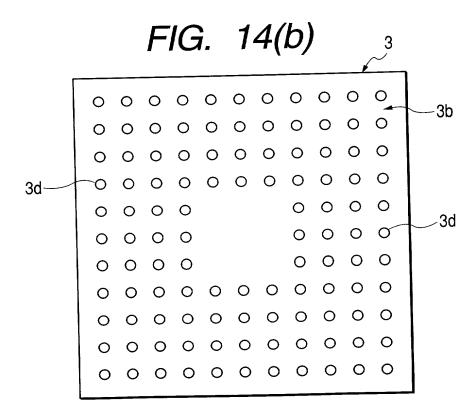


FIG. 15(a)

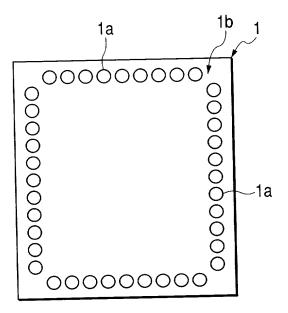


FIG. 15(b)

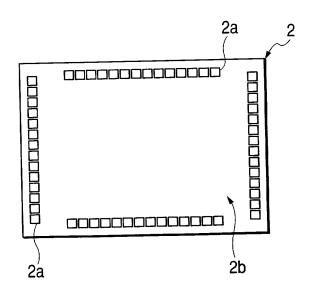


FIG. 16(a)

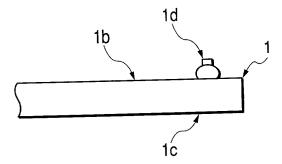
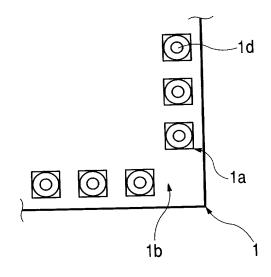


FIG. 16(b)



and reduction the distance

The street of th

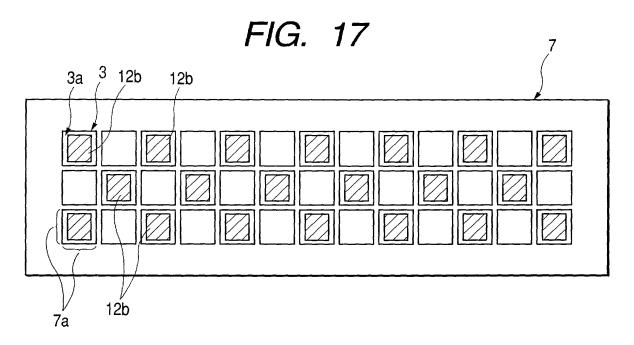


FIG. 18(a) FIG. 18(b) Зе Зе οσοσοσολοσσοσοσο ووووووووووووووووووو 0000000000000000000 12b 3á 3á 3é

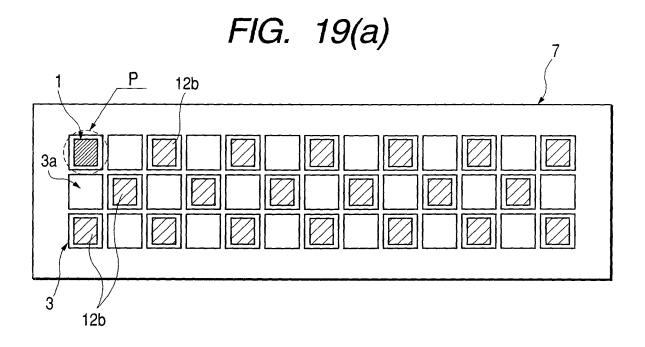


FIG. 19(b)

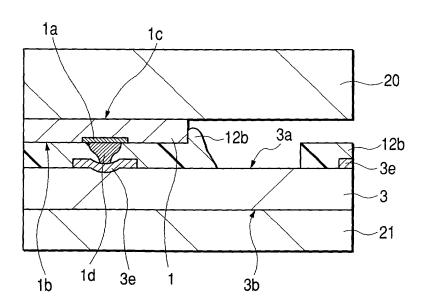


FIG. 20(a)

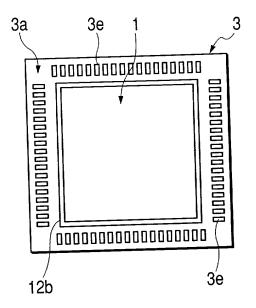
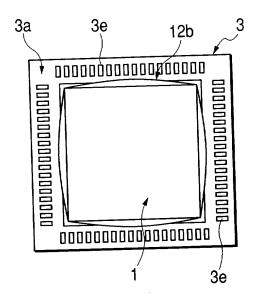
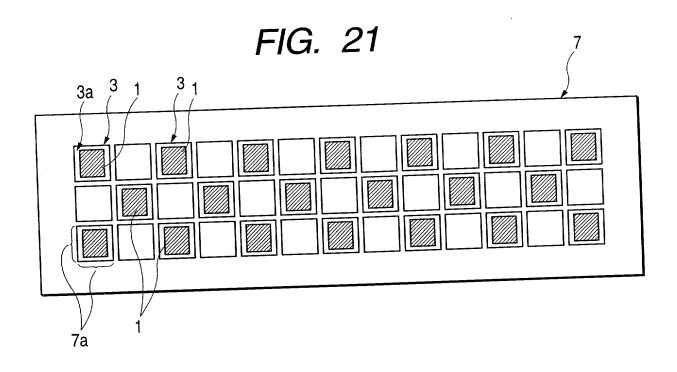
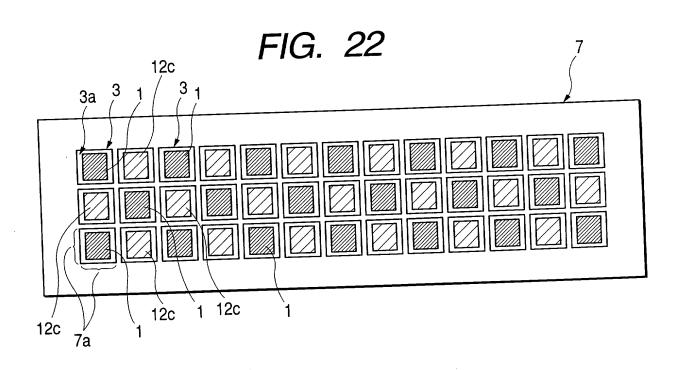


FIG. 20(b)







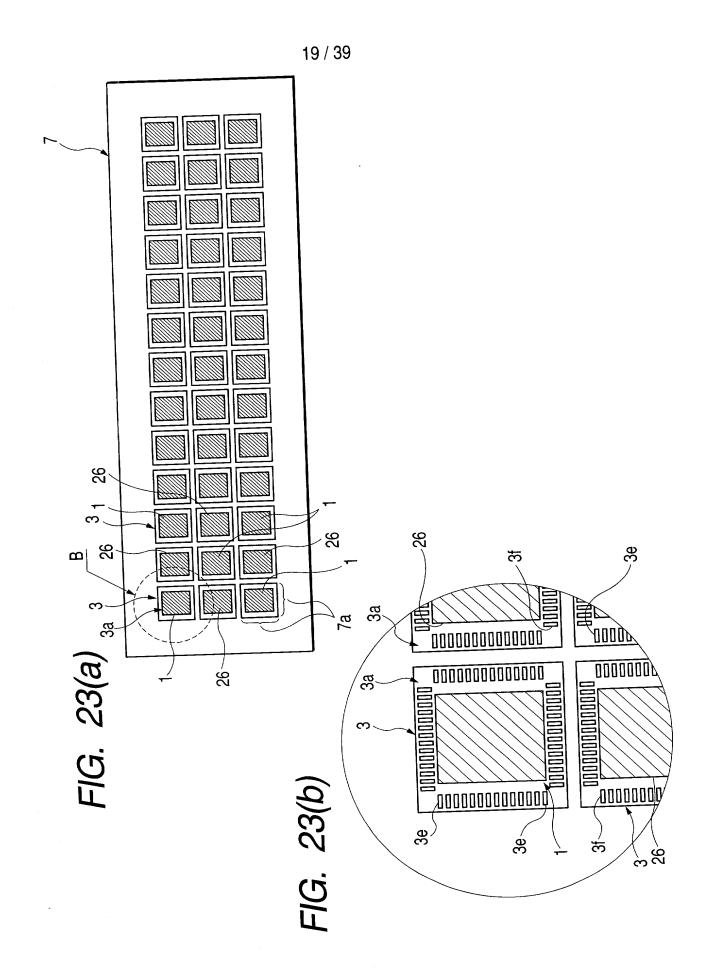


FIG. 24

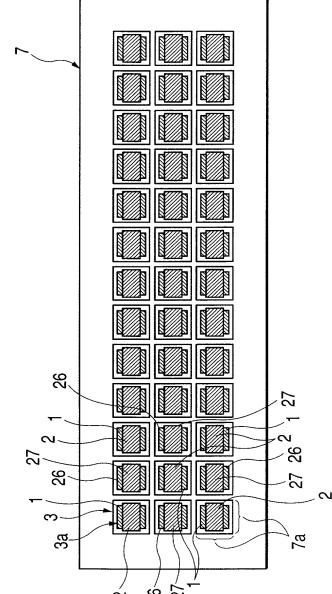


FIG. 26(a)

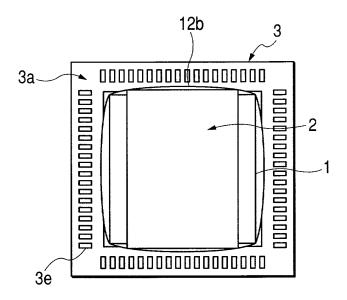
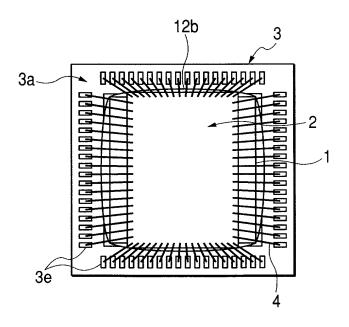


FIG. 26(b)



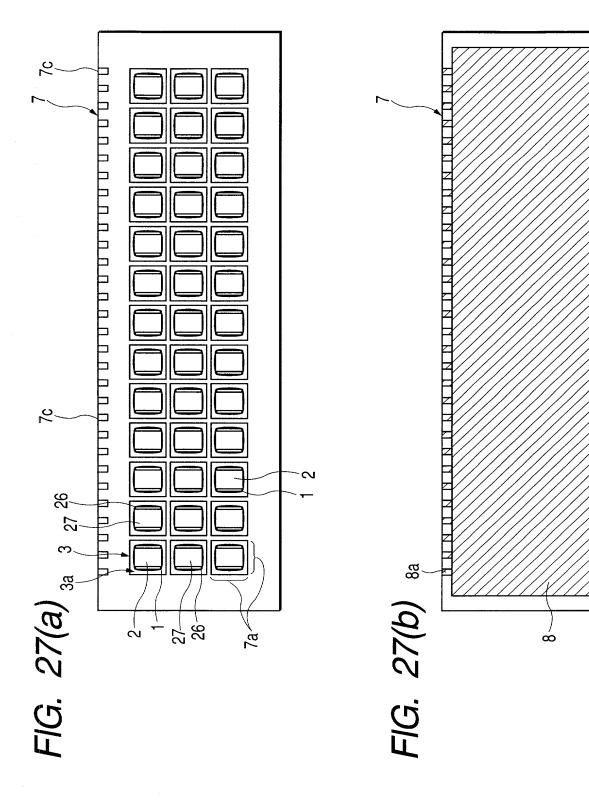


FIG. 28

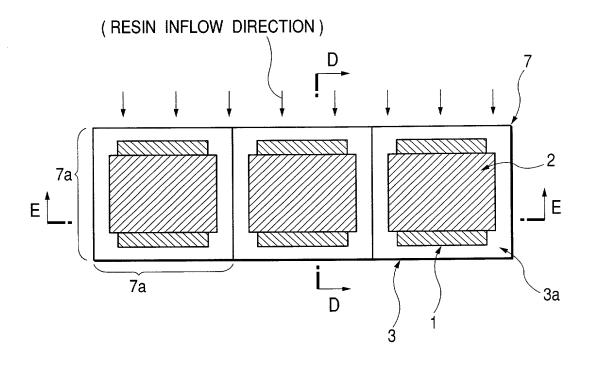


FIG. 29(a)

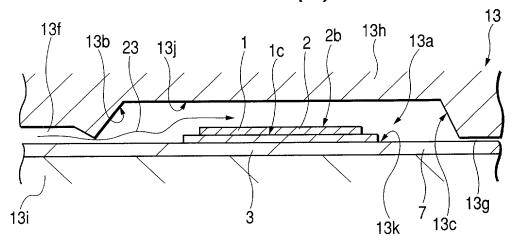


FIG. 29(b)

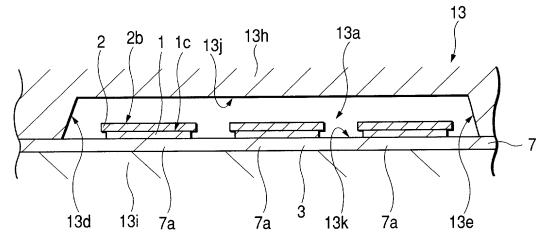
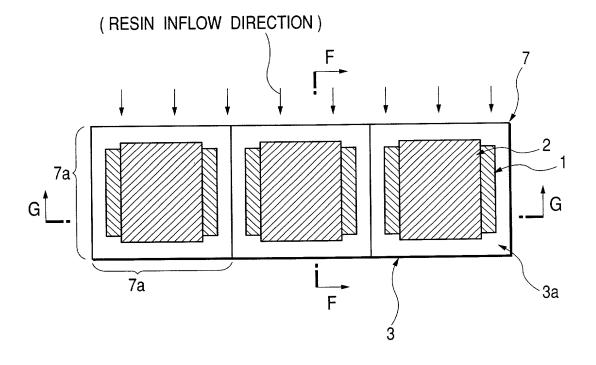


FIG. 30





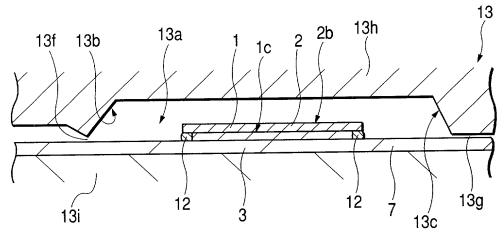


FIG. 31(b)

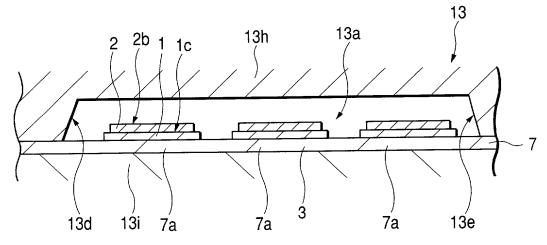


FIG. 32

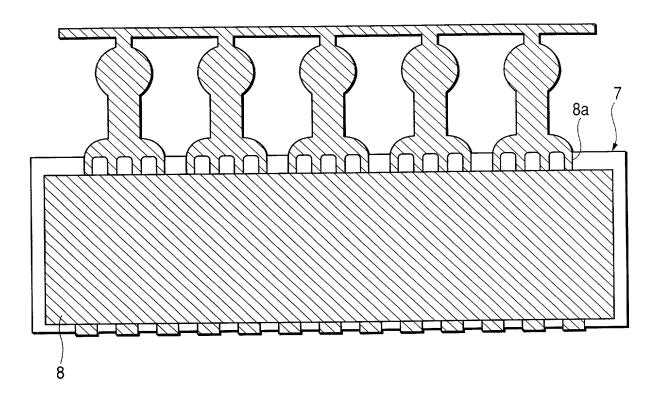
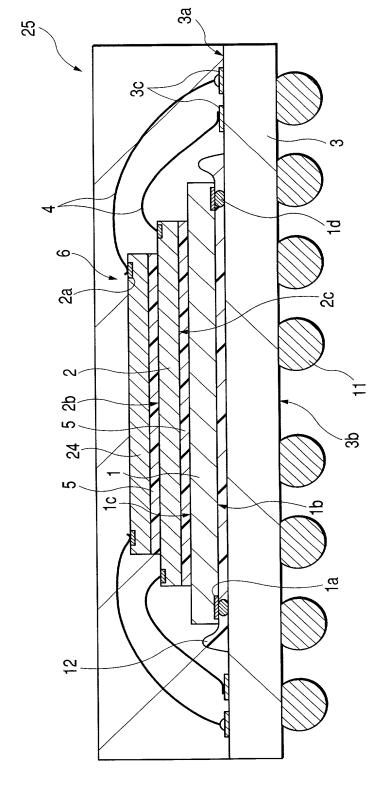
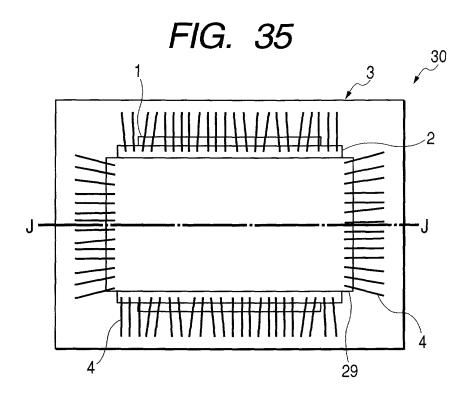


FIG. 33

Tele 3a 3 7b 1 3

FIG. 34





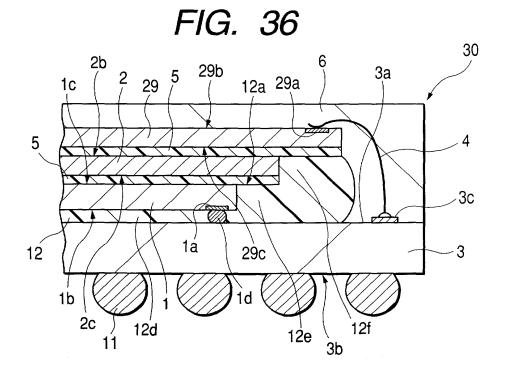


FIG. 37

FIG. 38

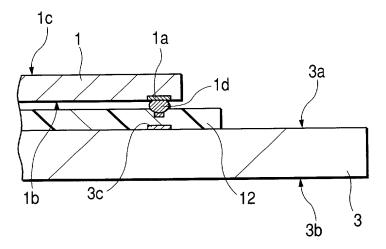


FIG. 39

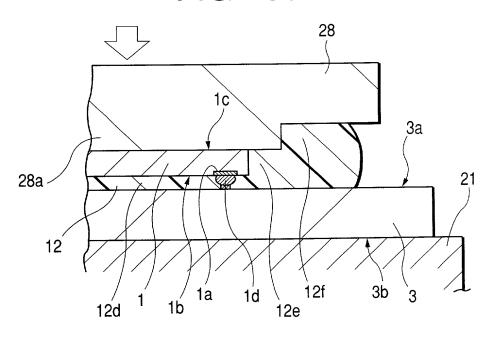


FIG. 40

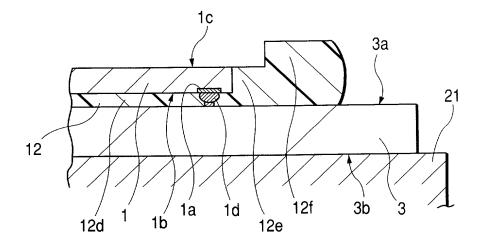


FIG. 41

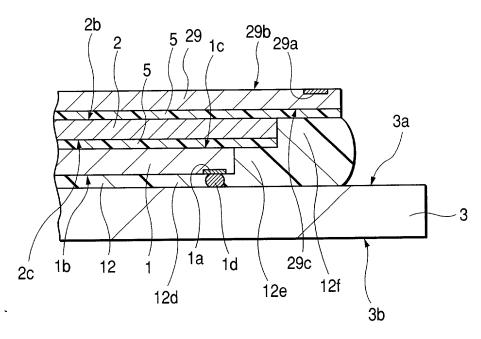


FIG. 42

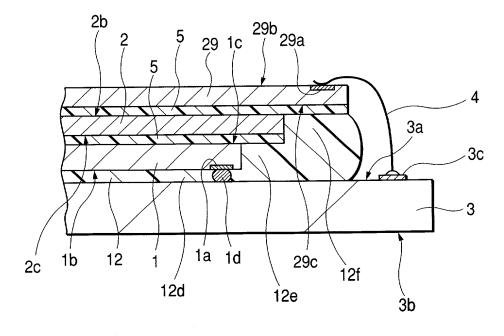


FIG. 43

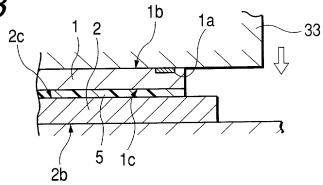


FIG. 44

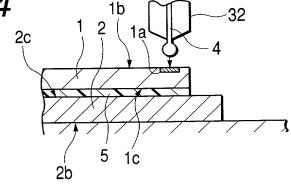


FIG. 45

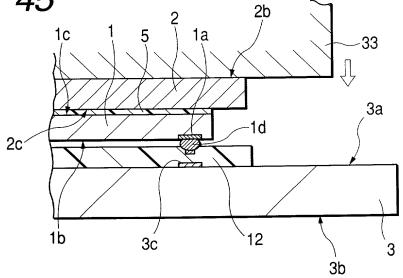


FIG. 46

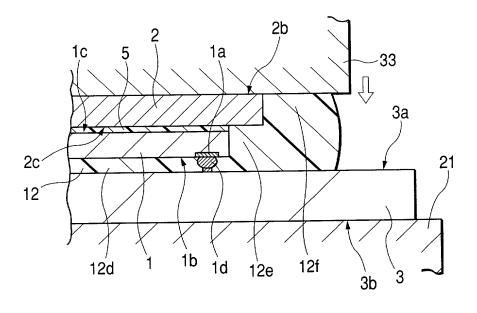


FIG. 47

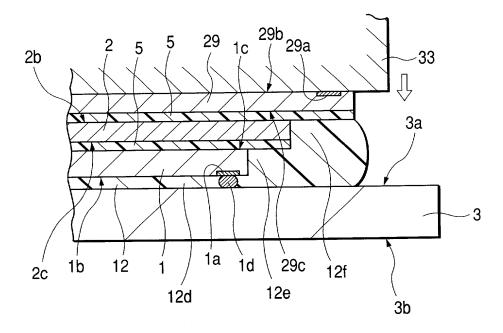


FIG. 48

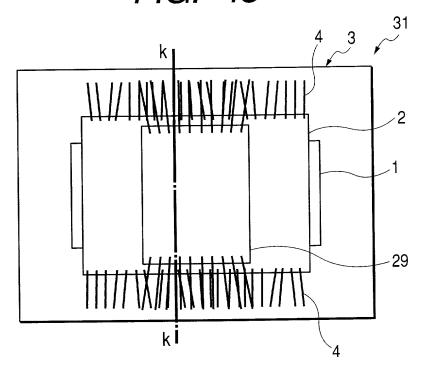


FIG. 49

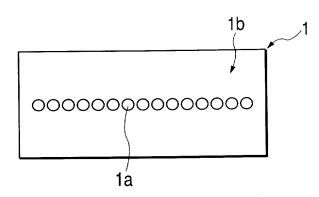


FIG. 50

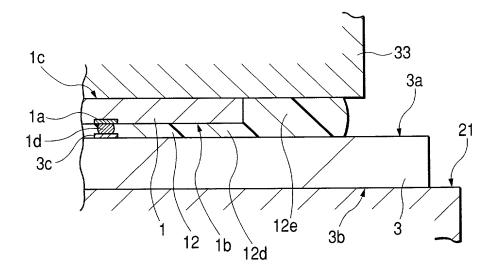


FIG. 51

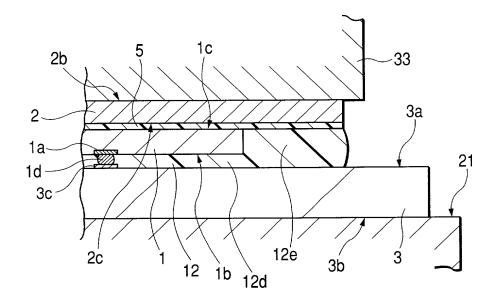


FIG. 52

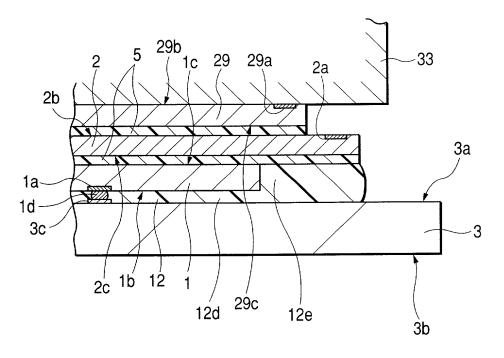


FIG. 53

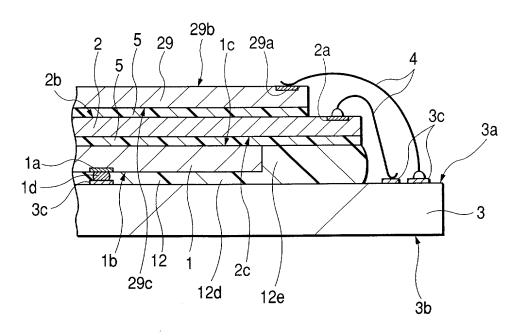


FIG. 54

